

PDFN3.3X3.3-8 N Channel Enhancement 沟道增强型 MOS Field Effect Transistor 场效应管

■ Features 特点

Low on-resistance 低导通电阻

$R_{DS(ON)}=3m\Omega(\text{Type})@V_{GS}=10V$

$R_{DS(ON)}=6m\Omega(\text{Type})@V_{GS}=4.5V$

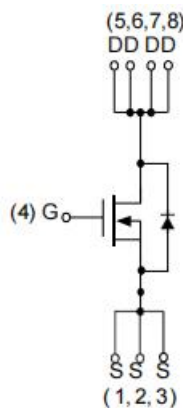
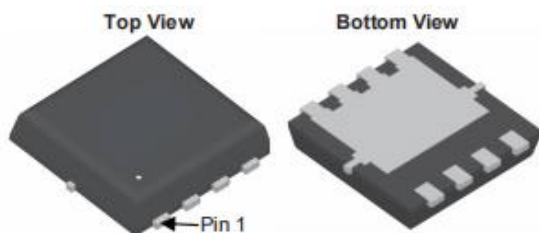
■ Applications 应用

Load Switch 负载开关

Portable Equipment 桌面设备

Power Management 电源管理

■ Internal Schematic Diagram 内部结构



■ Absolute Maximum Ratings 最大额定值

Characteristic 特性参数	Symbol 符号	Rat 额定值	Unit 单位
Drain-Source Voltage 漏极-源极电压	BV_{DSS}	30	V
Gate- Source Voltage 栅极-源极电压	V_{GS}	± 20	V
Drain Current (continuous)漏极电流-连续	I_D (at $T_C = 25^\circ C$ at $T_A = 25^\circ C$)	53 18	A
Drain Current (pulsed)漏极电流-脉冲	I_{DM}	100	A
Total Device Dissipation 总耗散功率	P_{TOT} (at $T_C = 25^\circ C$ at $T_A = 25^\circ C$)	29 1.6	W
Avalanche Energy(Single Pulse)雪崩能量	E_{AS}	31.25	mJ
Thermal Resistance Junction-Ambient 热阻	$R_{\theta JC}/R_{\theta JA}$	3.5/60	$^\circ C/W$
Junction/Storage Temperature 结温/储存温度	T_J, T_{stg}	-55~150	$^\circ C$

■ Electrical Characteristics 电特性

 (T_A=25℃ unless otherwise noted 如无特殊说明, 温度为 25℃)

Characteristic 特性参数	Symbol 符号	Min 最小值	Typ 典型值	Max 最大值	Unit 单位
Drain-Source Breakdown Voltage 漏极-源极击穿电压(I _D =250uA, V _{GS} =0V)	BV _{DSS}	30	—	—	V
Gate Threshold Voltage 栅极开启电压(I _D =250uA, V _{GS} =V _{DS})	V _{GS(th)}	1.5	1.8	2.5	V
Zero Gate Voltage Drain Current 零栅压漏极电流(V _{GS} =0V, V _{DS} =30V)	I _{DSS}	—	—	1	uA
Gate Body Leakage 栅极漏电流(V _{GS} =±20V, V _{DS} =0V)	I _{GSS}	—	—	±100	nA
Static Drain-Source On-State Resistance 静态漏源导通电阻(I _D =20A, V _{GS} =10V) (I _D =9A, V _{GS} =4.5V)	R _{DS(ON)}	—	3 6	4.5 7.5	mΩ
Diode Forward Voltage Drop 内附二极管正向压降(I _{SD} =2A, V _{GS} =0V)	V _{SD}	—	0.8	1.1	V
Input Capacitance 输入电容 (V _{GS} =0V, V _{DS} =15V, f=1MHz)	C _{ISS}	—	1500	—	pF
Common Source Output Capacitance 共源输出电容(V _{GS} =0V, V _{DS} =15V, f=1MHz)	C _{OSS}	—	215	—	pF
Reverse Transfer Capacitance 反馈电容 (V _{GS} =0V, V _{DS} =15V, f=1MHz)	C _{RSS}	—	185	—	pF
Total Gate Charge 栅极电荷密度 (V _{DS} =15V, I _D =12A, V _{GS} =4.5V)	Q _g	—	13	—	nC
Gate Source Charge 栅源电荷密度 (V _{DS} =15V, I _D =12A, V _{GS} =4.5V)	Q _{gs}	—	4	—	nC
Gate Drain Charge 栅漏电荷密度 (V _{DS} =15V, I _D =12A, V _{GS} =4.5V)	Q _{gd}	—	7	—	nC
Turn-ON Delay Time 开启延迟时间 (V _{DS} =15V I _D =1A, R _{GEN} =6Ω, V _{GS} =10V)	t _{d(on)}	—	14	—	ns
Turn-ON Rise Time 开启上升时间 (V _{DS} =15V I _D =1A, R _{GEN} =6Ω, V _{GS} =10V)	t _r	—	10	—	ns
Turn-OFF Delay Time 关断延迟时间 (V _{DS} =15V I _D =1A, R _{GEN} =6Ω, V _{GS} =10V)	t _{d(off)}	—	44	—	ns
Turn-OFF Fall Time 关断下降时间 (V _{DS} =15V I _D =1A, R _{GEN} =6Ω, V _{GS} =10V)	t _f	—	12	—	ns

■ Typical Characteristic Curve 典型特性曲线

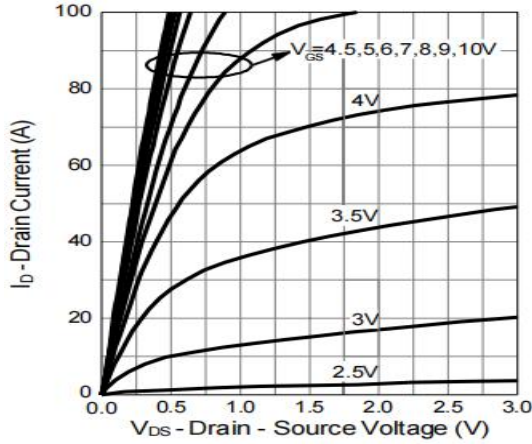


Figure 1: Output Characteristics

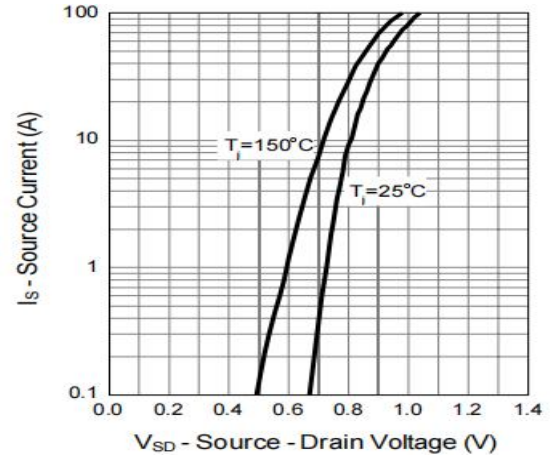


Figure 2: Diode Forward Characteristics

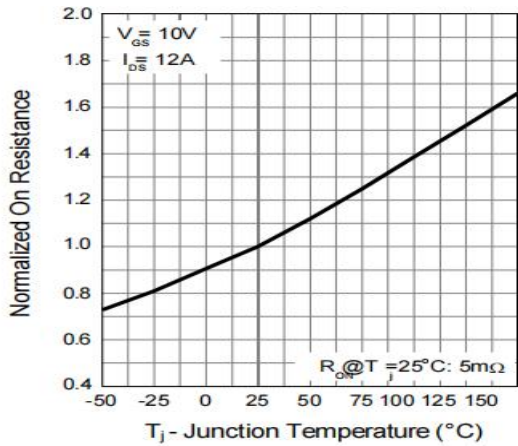


Figure 3: On-Resistance vs. T_j

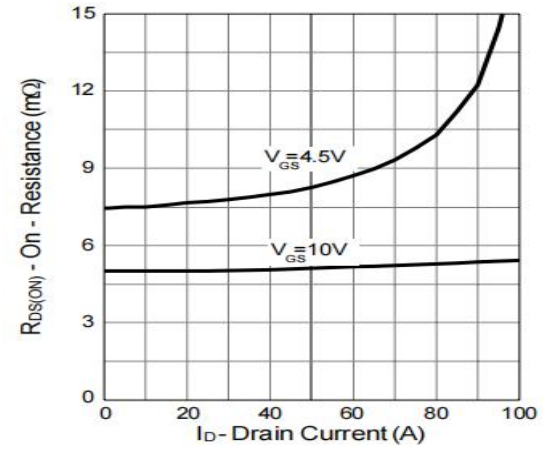


Figure 4: On-Resistance vs. Drain Current

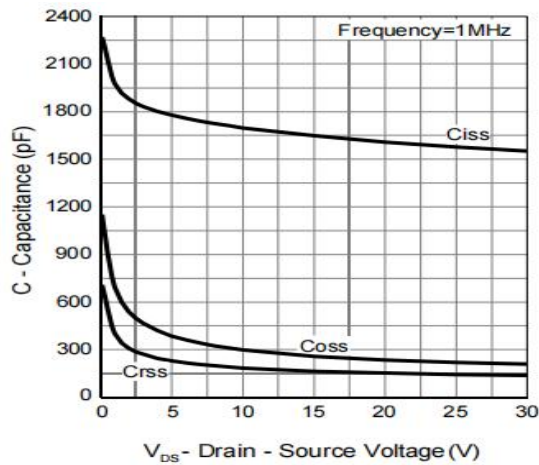


Figure 5: Capacitance Characteristics

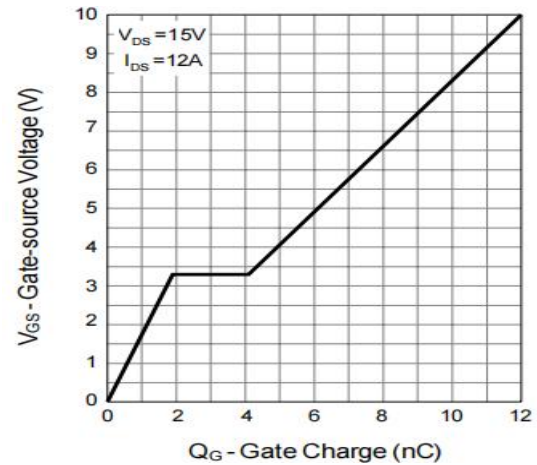


Figure 6: Gate-Charge Characteristics

■ Typical Characteristic Curve 典型特性曲线

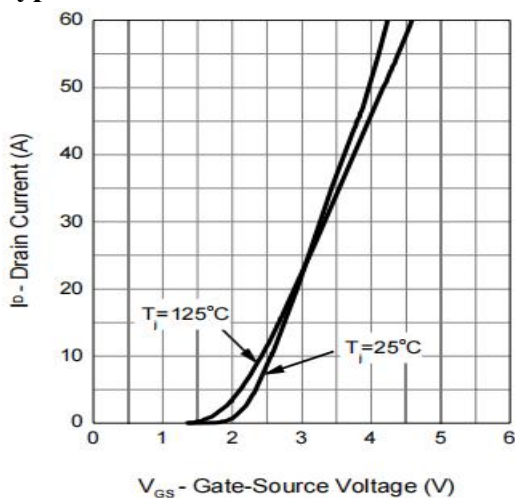


Figure 7: Transfer Characteristics

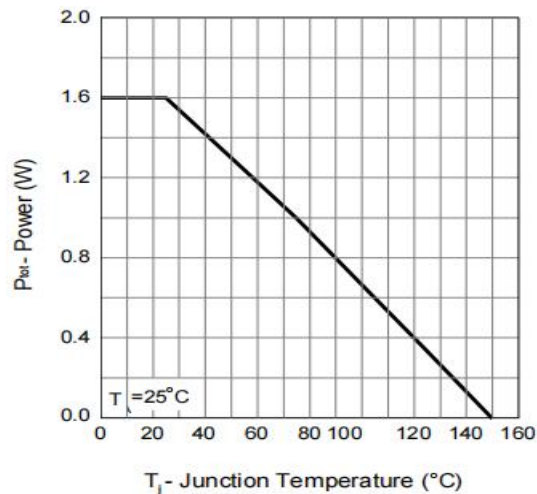


Figure 8: Power Rating Curve

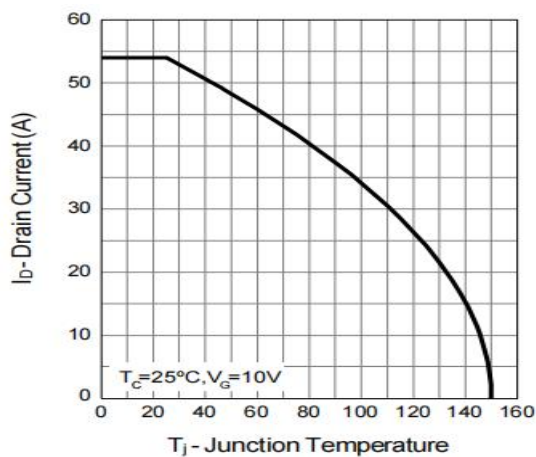


Figure 9: Drain Current Characteristics

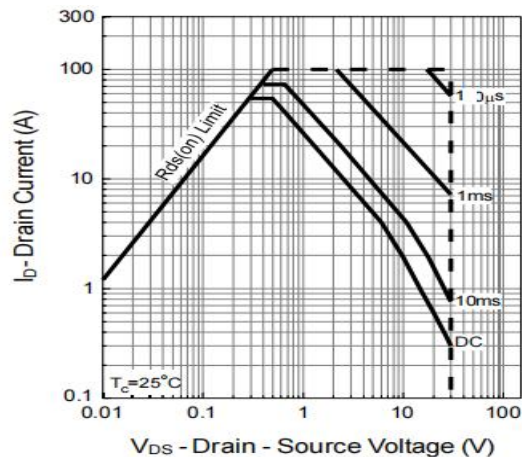


Figure 10: Safe Operating Area

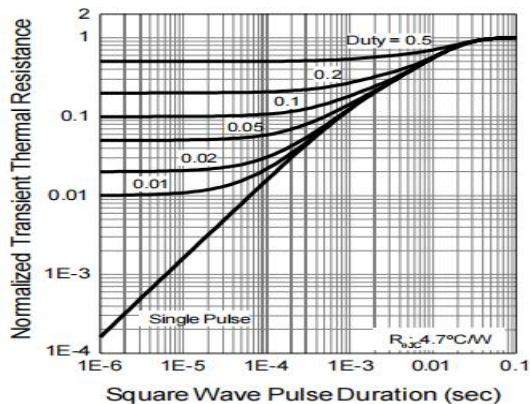
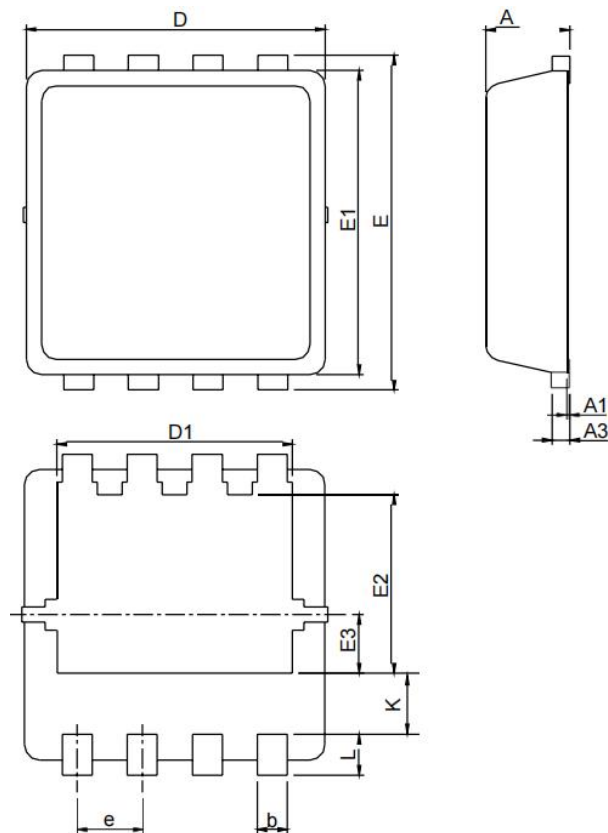


Figure 11: Transient Thermal Response Curve

■ Dimension 外形封装尺寸



SYMBOL	PDFN3x3-8			
	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	0.80	1.00	0.031	0.039
A1	0.00	0.05	0.000	0.002
A3	0.10	0.25	0.004	0.010
b	0.24	0.35	0.009	0.014
D	2.90	3.10	0.114	0.122
D1	2.25	2.45	0.089	0.096
E	3.10	3.30	0.122	0.130
E1	2.90	3.10	0.114	0.122
E2	1.65	1.85	0.065	0.073
E3	0.56	0.58	0.022	0.023
e	0.65 BSC		0.026 BSC	
K	0.475	0.775	0.019	0.031
L	0.30	0.50	0.012	0.020